

**SURFACE MOUNT  
SILICONE COATED TYPE**

**HIAS  
SERIES  
SURFACE MOUNT WIRE WOUND  
RESISTORS**

- 1 & 2W -  
Silicone Coated Melf Design
- 2,3,4 & 5W -  
Tin Plated Terminations
- R01 to 22K

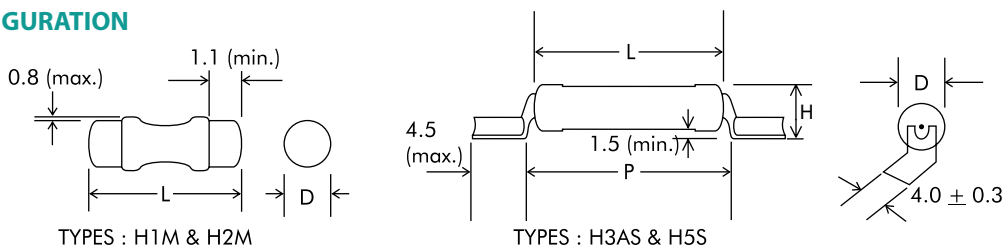
**As per AEC-Q200**





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**PHYSICAL CONFIGURATION**



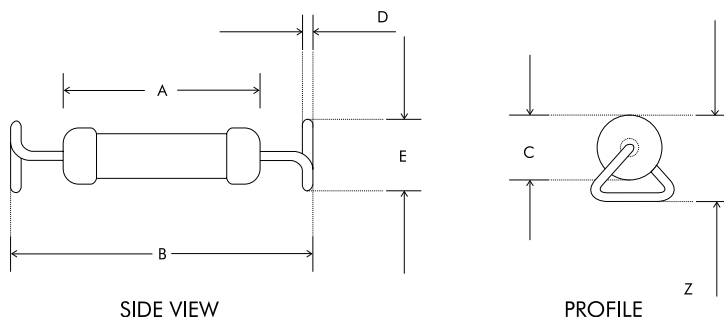
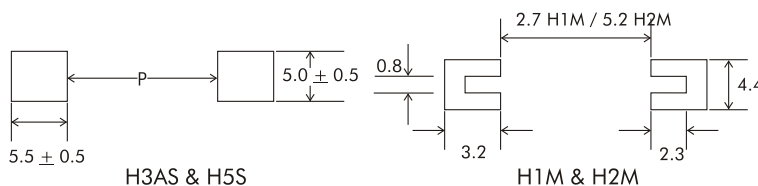
HTR TYPE	POWER RATING at 40°C	DIMENSIONS (mm)				RESISTANCE RANGE		TYPICAL WEIGHT PER PC (gms)
		L ±1.0	∅ D (max)	P ±1.0	# H (max)	min	max	
H-1M	1W	6.5	4.1	-	-	R10	1K5	0.5
H-2M	2W	9.0	4.1	-	-	R10	3K5	0.6
H-3AS	3W	13.0	5.7	18.0	8.00	R01	10K	1.2
H-5S	5W	19.5	6.5	24.5	8.25	R01	22K	2.0

◇ D for non-inductive types and for resistance values <1R0 +0.8mm allowed.

# H for non-inductive types and for resistance values <1R0 +0.8mm allowed.

**MOUNTING SPECIFICATIONS**

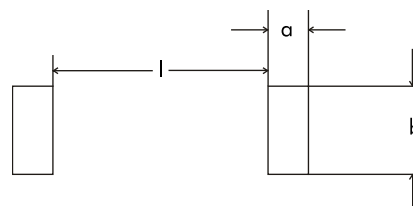
For the guidance of the Design Engineer, our applications laboratory has given the recommended pad size and geometry which is shown below:



HTR TYPE	POWER RATING at 40°C	DIMENSIONS (mm)						RESISTANCE RANGE		TYPICAL WEIGHT PER PC (gms)
		A [max]	B [±1.0]	C [max]	D [±0.05]	E [±0.5]	Z [±1.0]	[min]	[max]	
2WS	2W	12.0	17.0	4.8	0.8	5.0	6.5	R10	5K6	0.95
2WSA	2W	9.0	13.4	4.5	0.8	4.5	6.5	R05	2K2	0.7
3WS	3W	14.5	18.7	6.0	0.8	6.5	8.0	R01	10K	1.2
3WSA	3W	13.0	18.7	5.1	0.8	6.5	6.9(max)	R01	8K2	1.1
4WS	4W	15.5	20.0	6.0	0.8	8.0	8.0	R10	12K	1.25
5WS	5W	16.5	18.7	7.0	0.8	6.5	8.0	R01	12K	1.65

**MOUNTING / ASSEMBLY DATA**

For the guidance of the Design Engineer, our applications laboratory has given the recommended pad size and geometry which is shown below



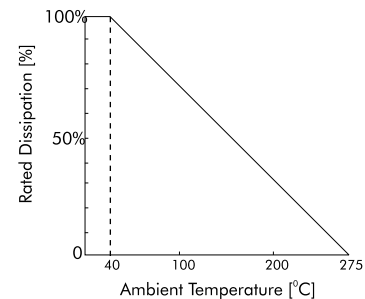


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HTR TYPE	DIMENSIONS (mm)		
	a	b	l
2WS	2.5	5.5	14.0
2WSA	2.5 (min)	5.5 (min)	10.0 (max)
3WS	2.5 (min)	8.0 (min)	15.0 (max)
3WSA	2.5 (min)	8.0 (min)	15.0 (max)
4WS	2.5	9.5	17.0
5WS	2.5 (min)	8.0 (min)	15.0 (max)

#### DERATING CURVE



#### ELECTRICAL AND ENVIRONMENTAL CHARACTERISTICS / DATA

PARAMETER/ PERFORMANCE TEST	TEST METHOD - DETAILS	PERFORMANCE REQUIREMENTS
<b>Power Rating</b> (Rated Ambient Temperature)	Subject to size of solder pads used and type of PCB / pads (Performance requirements shown are based on use of FR4 test boards measuring 50mm x 50mm with 300g/m <sup>2</sup> copper pads)	Full power dissipation at 40°C and linearly derated to zero at 275°C (Refer derating curve shown)
<b>Resistance Tolerances Available</b>	JIS-C-5202- Para 5.1	±10% [K]; ±5% [J]; ±3% [H]; ±2%[G]; ±1% [F]
<b>Operating Temperature Range</b>		-55°C to +275°C (with suitable derating as per derating curve shown)
<b>Voltage Rating / Limiting Voltage / Max Working Voltage</b>	$V = \sqrt{P \times R}$	
<b>Maximum Overload Voltage</b> (Pulse)	IEC 6100-4-5 (1.2/50µsec)	Varies depending on resistance value, duration between pulses & no. of pulses to be withstood (contact factory for details)
<b>Rated load</b>	JIS-C-5202- Para 5.4	$\Delta R \pm [1\% + R05]$
<b>Voltage Proof /Dielectric Withstanding Voltage</b>	JIS-C-5202- Para 5.7 (based on limiting voltage x 2 or 500V whichever is applicable)	$\Delta R \pm [1\% + R05]$
<b>Temperature Rise</b>	Will vary based on solder pad dimensions used	Consult factory with full details of pad size used
<b>Short Time Overload</b>	JIS-C-5202- Para 5.5 (upto 3W - condition A - R.V x 2.5 for 5 secs) (4W and above - condition B - voltage corresponding to 10 times power for 5 secs)	$\Delta R \pm [1.2\% + R05]$ - Average
<b>Insulation Resistance</b>	JIS-C-5202- Para 5.6 (condition F)	> 1000M.Ω (dry)
<b>Temperature Co-efficient of Resistance</b>	JIS-C-5202- Para 5.2	± 90 ppm/°C [>10R] ± 80 ppm/°C [<10R] ± 200 ppm/°C [<R10]
<b>Endurance - under load with humidity</b>	JIS-C-5202- Para 7.9 1000 hours at 40°C ± 2°C, 95%, R.H with limiting voltage - 1.5 hours on / 0.5 hours off	$\Delta R \pm [5\% + R05]$
<b>Damp Heat</b> (Steady State)	JIS-C-5202- Para 7.5	$\Delta R \pm [3\% + R05]$
<b>Temperature Cycling</b>	JIS-C-5202- Para 7.4 (Room temperature → 55°C → Room temperature → 155°C → Room temperature for 5 cycles)	$\Delta R \pm [2\% + R05]$ - Typical
<b>Load Life</b>	JIS-C-5202- Para 7.10 1000 hours at 70°C with limiting voltage - 1.5 hours on / 0.5 hours off	$\Delta R \pm [≤3\% + R05]$ - Average
<b>Climate Category</b>		55/200/56
<b>Solvent Resistant</b>	JIS-C-5202- Para 6.9 Solvent A - 1PA for 60 secs ± 10 secs	No effect on coating or marking
<b>Flame Retardant</b> (under overload condition)	JIS-C-5202- Para 7.12.3.2	No flaming / arcing



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## MECHANICAL SPECIFICATIONS

PARAMETER/ PERFORMANCE TEST	TEST METHOD - DETAILS	PERFORMANCE REQUIREMENTS
Resistance to Soldering Heat	260°C - 270°C for 10 secs.	$\Delta R \pm [0.75\% + R05]$ - Typical
Solderability	JIS-C-5202- Para 6.5	Continuous and satisfactory (95% min coverage).

## TYPICAL APPLICATIONS

This series has been evolved in order to fill the gap for melf and surface mount resistors in applications which are too severe for film resistors. The advantages are superior power to size zero ratio, higher tolerance to pulse, surge applications and negligible noise.

## ORDERING INFORMATION

Series	HTR Type	Packing	Resistance Value	Tolerance
HIAS	H3AS / H3AS*	Bulk H3AS / H3AS*	100R	J

For RoHS version - H3AS \*